

PATENT APPLN. NO. 10/802,059
RESPONSE UNDER 37 C.F.R. §1.111

**PATENT
NON-FINAL**

IN THE ABSTRACT OF THE DISCLOSURE:

Please replace the abstract of the disclosure with the following amended abstract:

A transport and storage carrier for semiconductor members including wafers which ~~is characterized in that the carrier is~~ molded from a resin composition ~~comprising~~ containing a synthetic resin having a melting temperature of at least 300°C and a carbon fibril admixed with the resin, the molded carrier being 1 to 5 seconds in average charge decay time for decay of 1,000 V to 5 V.